

# Efficiency optimized laser processing for thin-film silicon solar modules

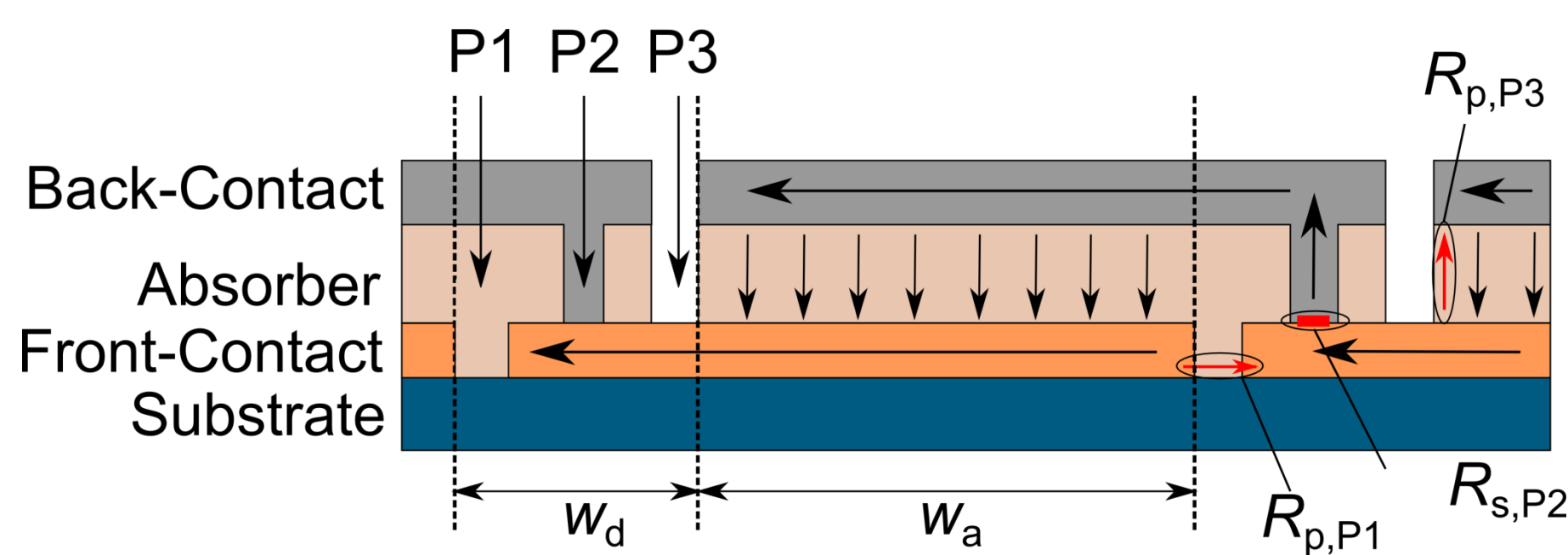
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Motivation

## Minimization of interconnection losses of thin-film silicon solar modules



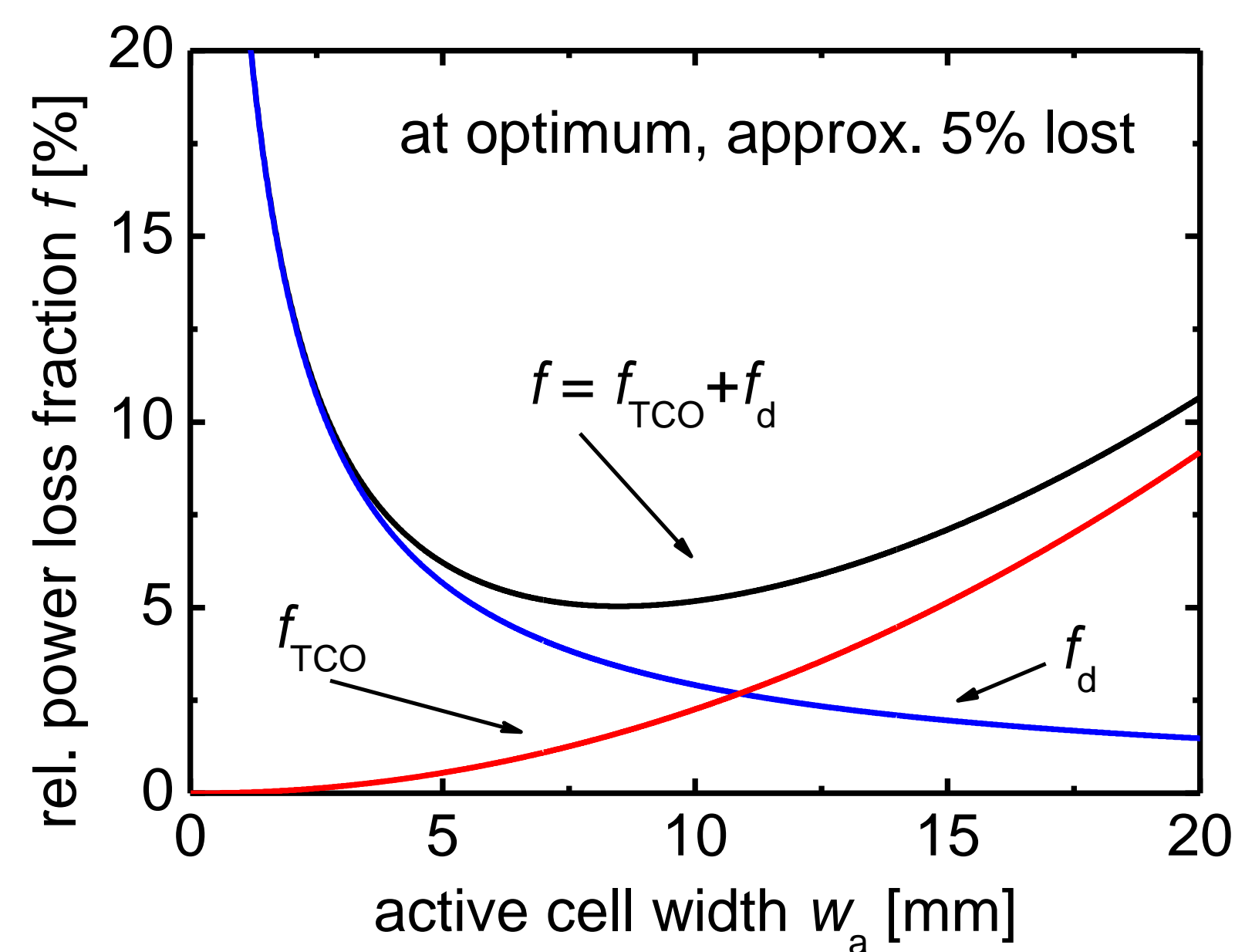
Module cell stripe in p-i-n superstrate topology

### Origins of module losses

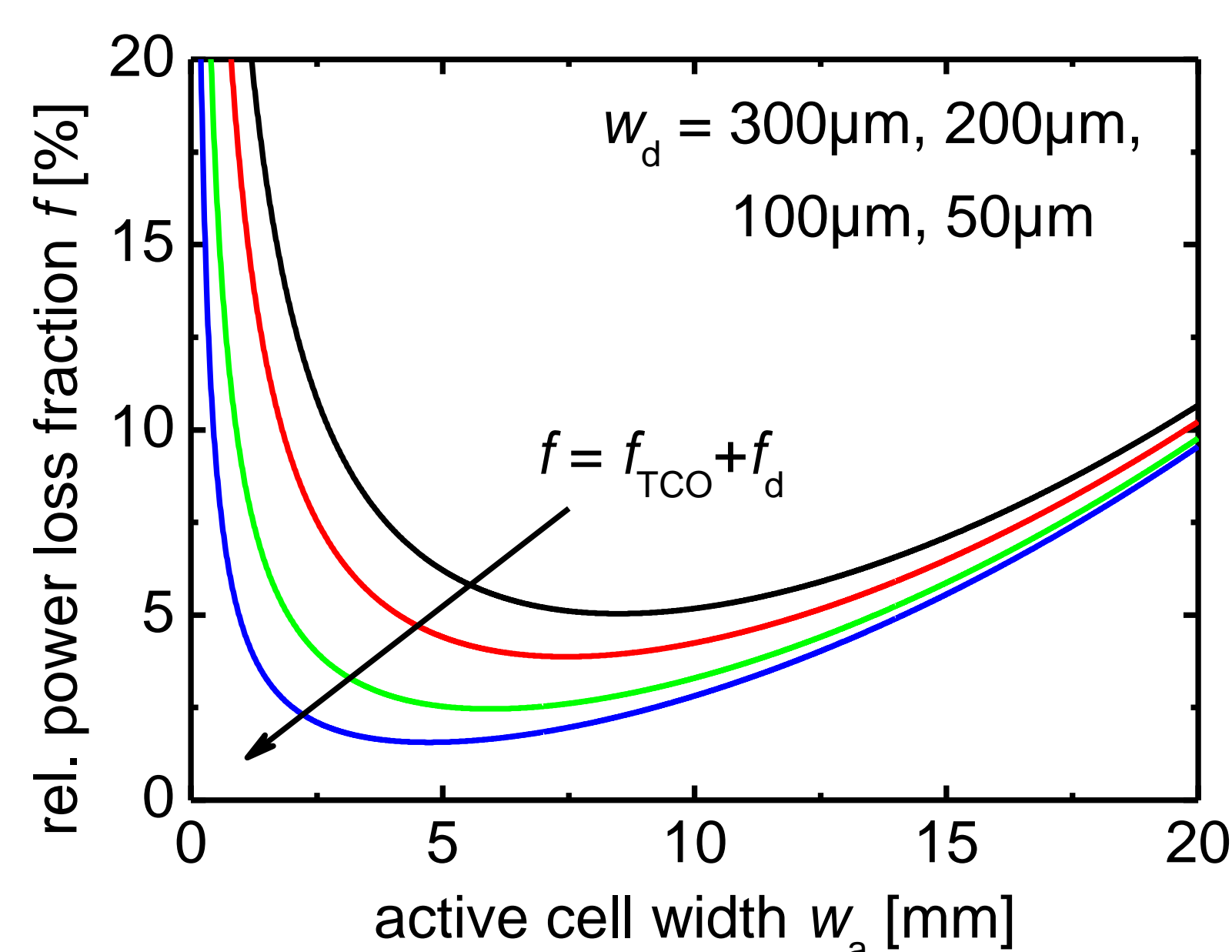
#### Inherent interconnection losses

$$f = \underbrace{\frac{w_d}{w_a + w_d}}_{f_d} + \underbrace{\frac{J_{MPP}}{U_{MPP}} \cdot \frac{R_{\square}}{3} \cdot \frac{w_d \cdot w_a^2 + w_a^3}{w_a + w_d}}_{f_{TCO}}$$

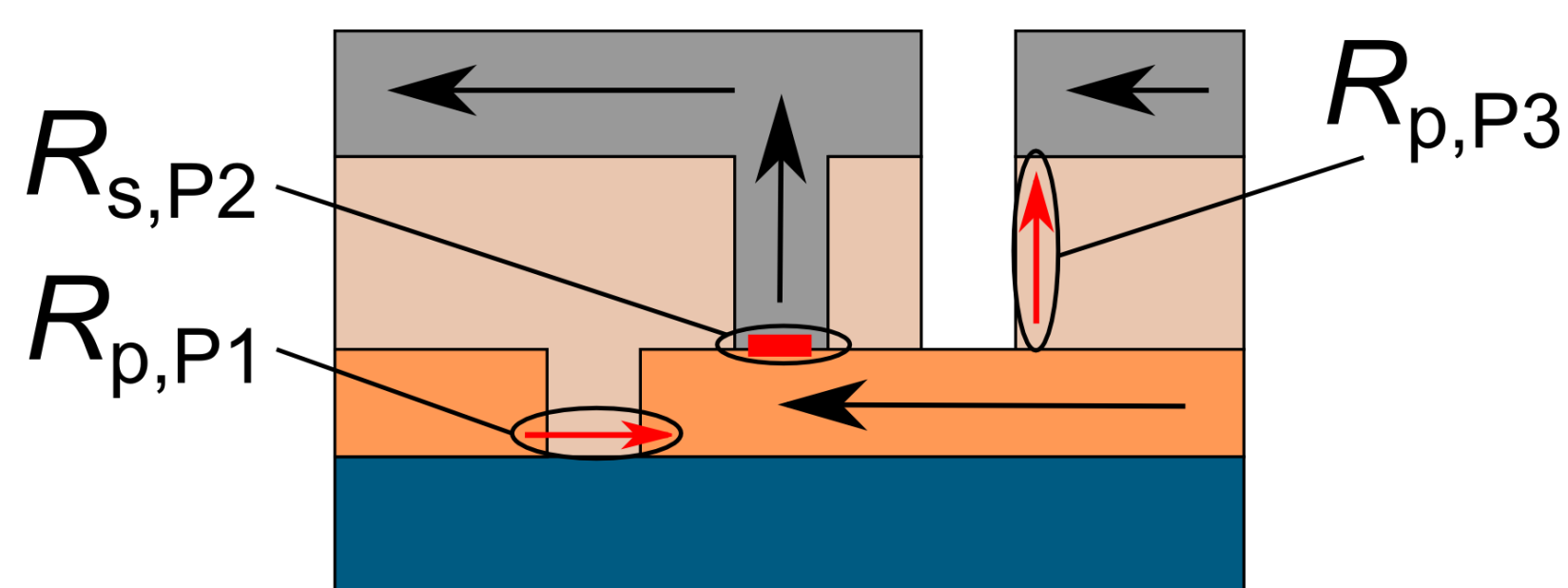
- Area loss fraction  $f_d$
- Loss fraction due to current collection in the TCO front-contact  $f_{TCO}$



#### Influence of interconnection width reduction



#### Damages due to interconnection processes



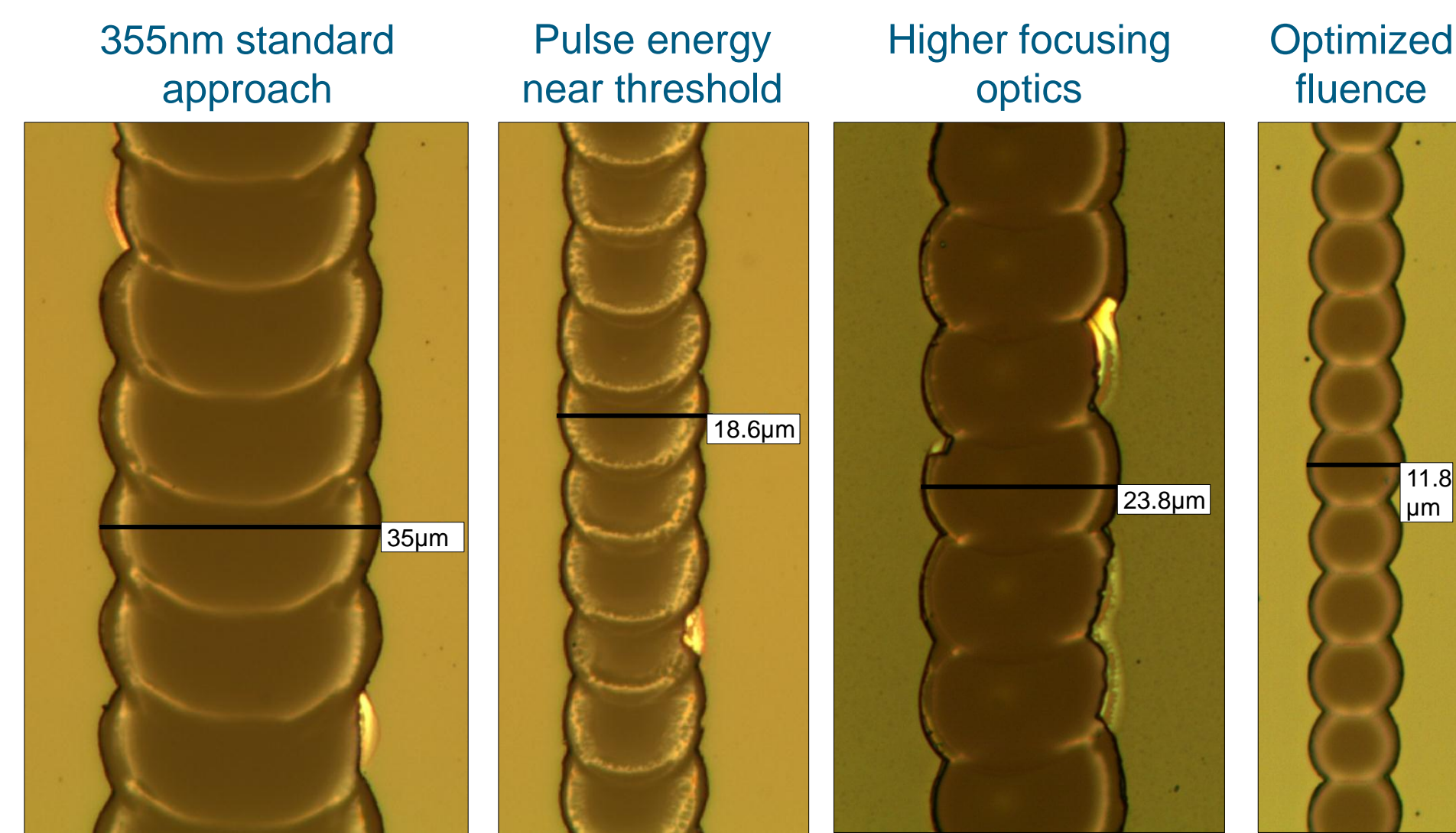
- P1: losses after absorber deposition parallel to cell  $R_{p,P1} \sim w_{P1}$
- P2: formation of series resistance between two cells  $R_{s,P2} \sim 1/w_{P2}$
- P3: shunt between front- and back-contact  $R_{p,P3}$  due to alloying and phase changes

Conclusion

- An interconnection width reduction was achieved for the front-contact separation process P1 of ZnO:Al TCO material
- A test-structure was used to determine the residual conductivity within the scribe to determine the optimal width  $w_{P1} \rightarrow$  conductivity negligible for studied system
- It was found out, that current flow changes near the edge are due to surface effects rather than bulk material changes

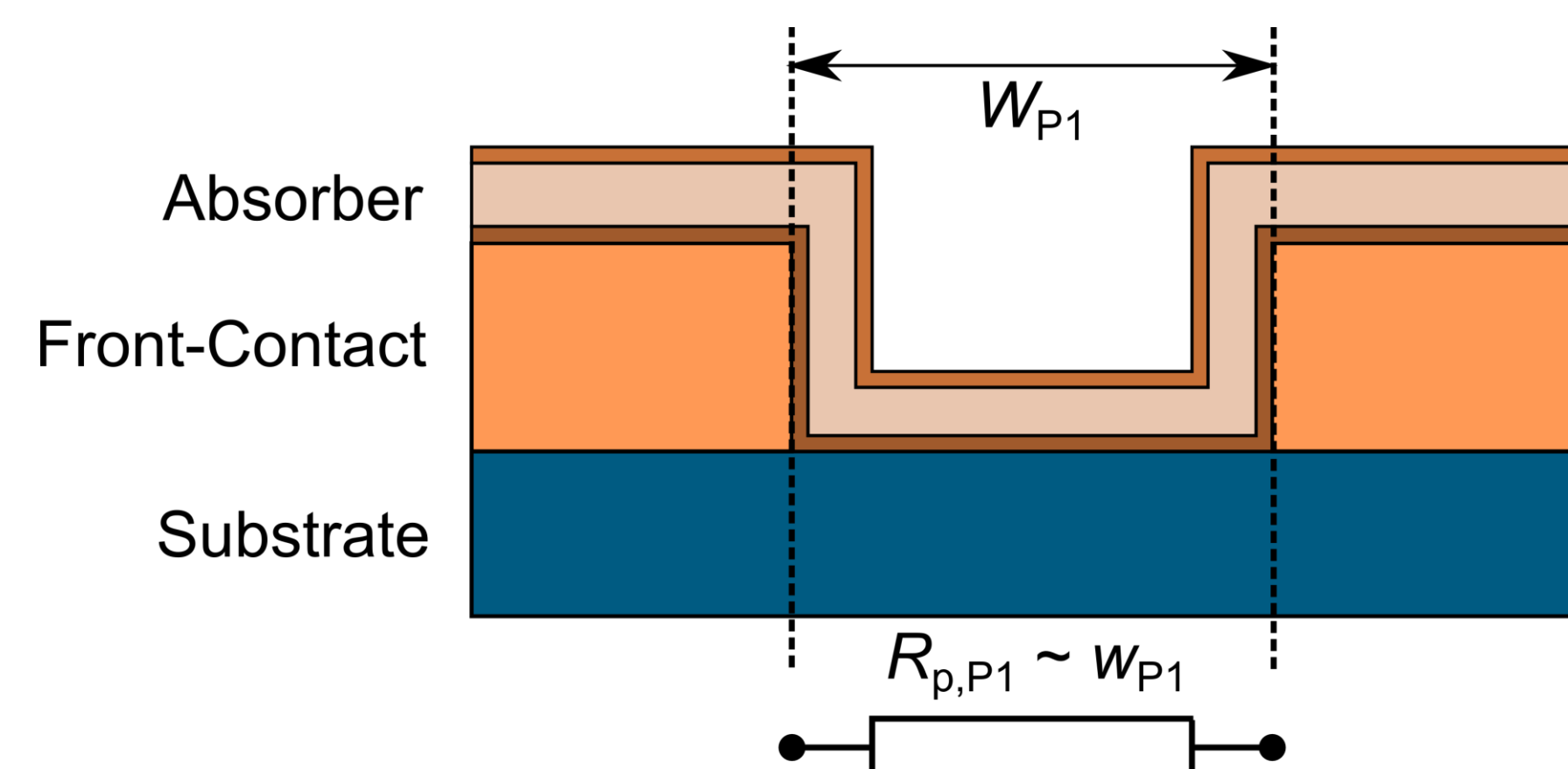
Results

### P1 interconnection width reduction

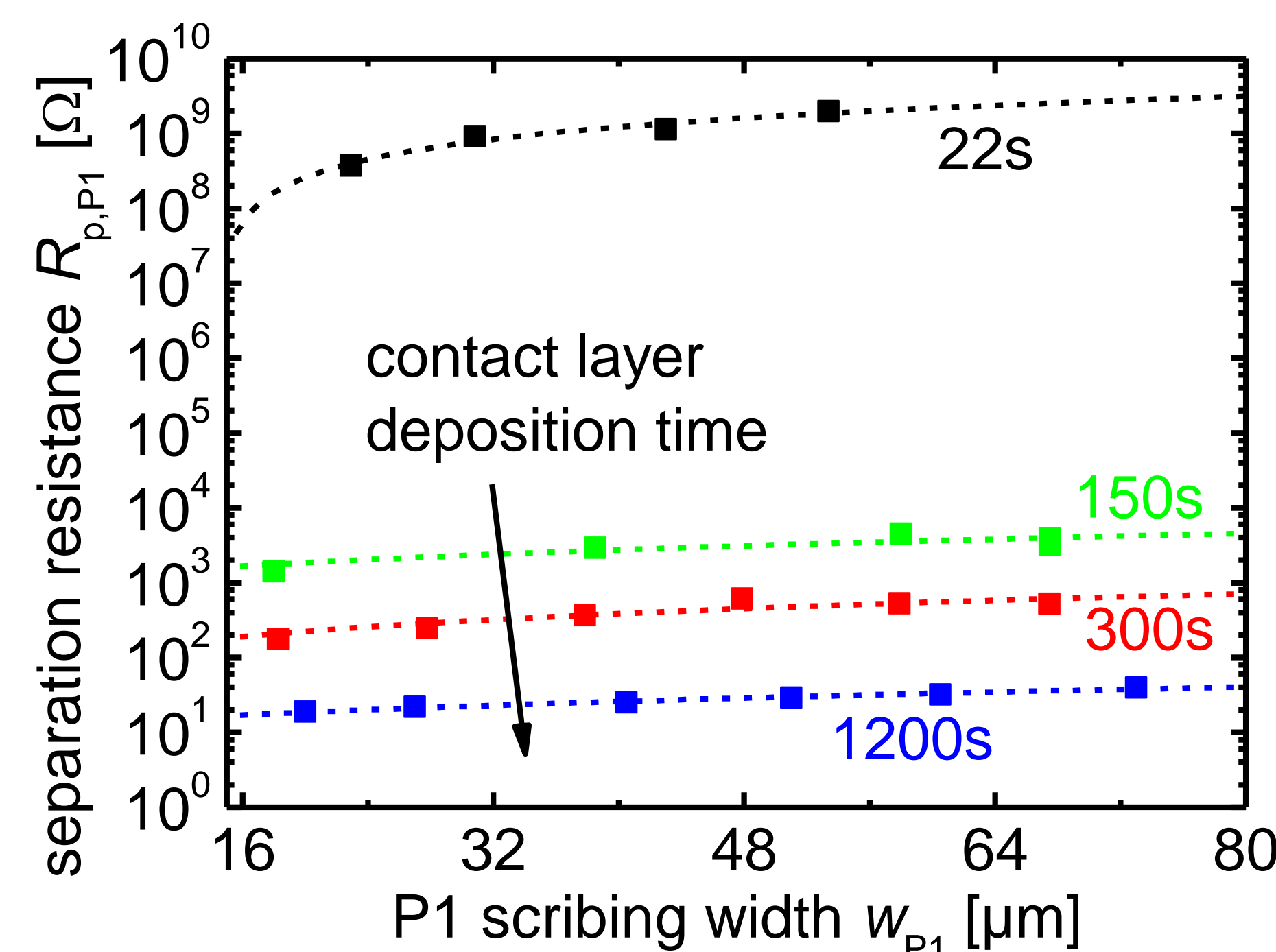


- Evolution of width reduction studies on in-house ZnO:Al TCO material before etch

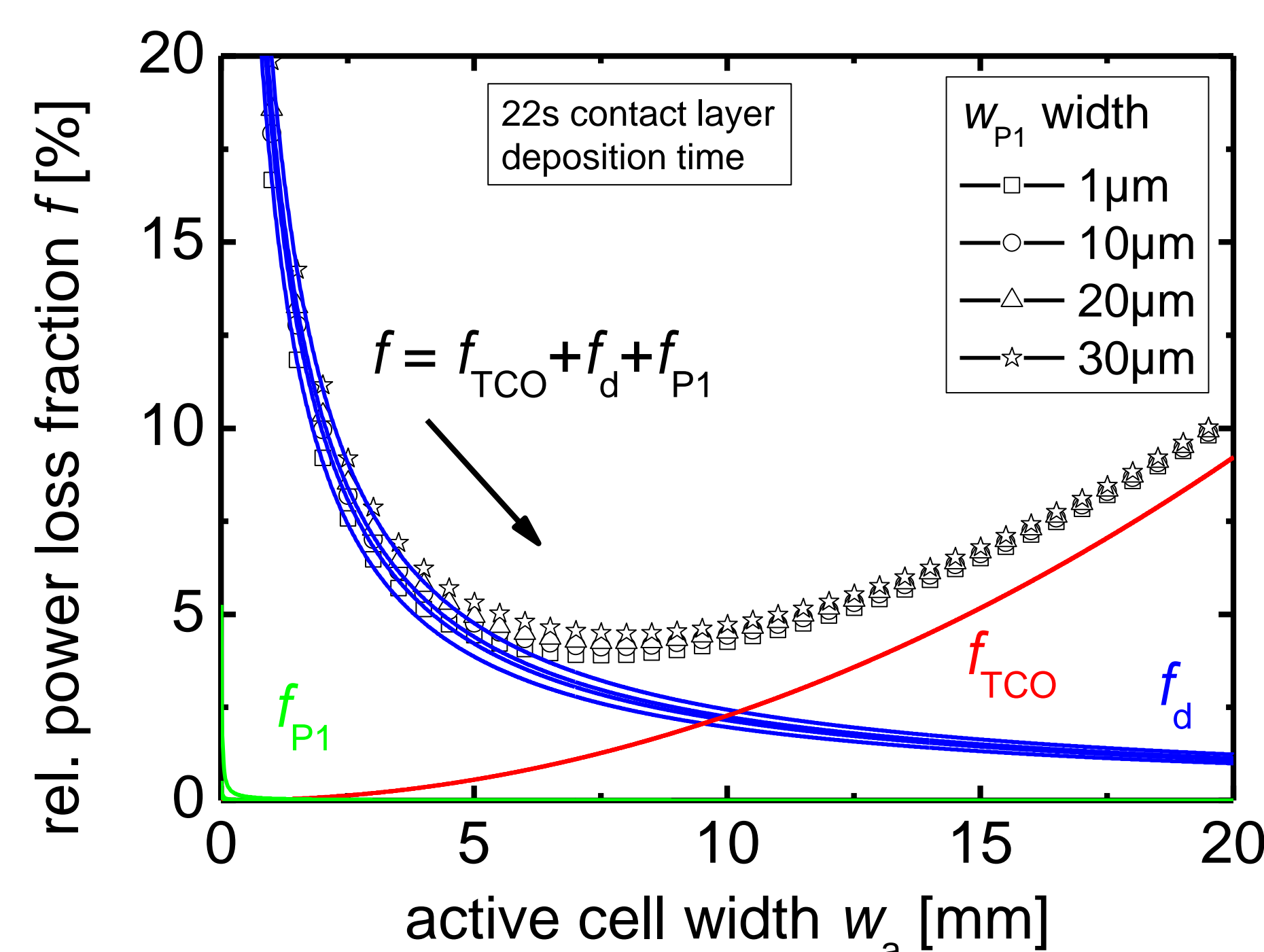
### Impact of parasitic conductivity



#### Investigation of highly conductive $\mu$ c-Si:H(p) contact layer for a-Si:H / ZnO:Al



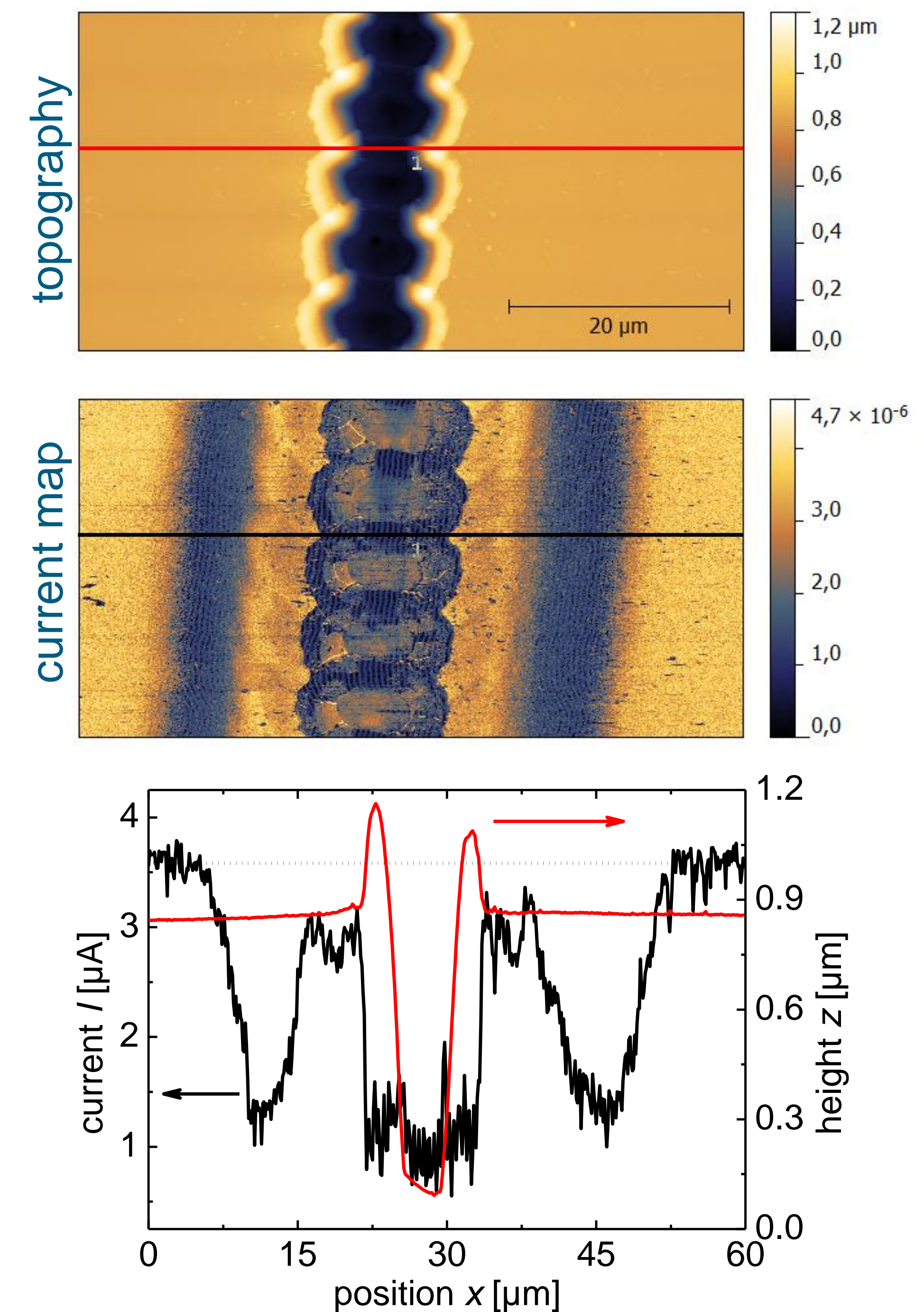
#### Extend model calculations to account for $R_{p,P1}$ induced electrical losses $f_{P1}$



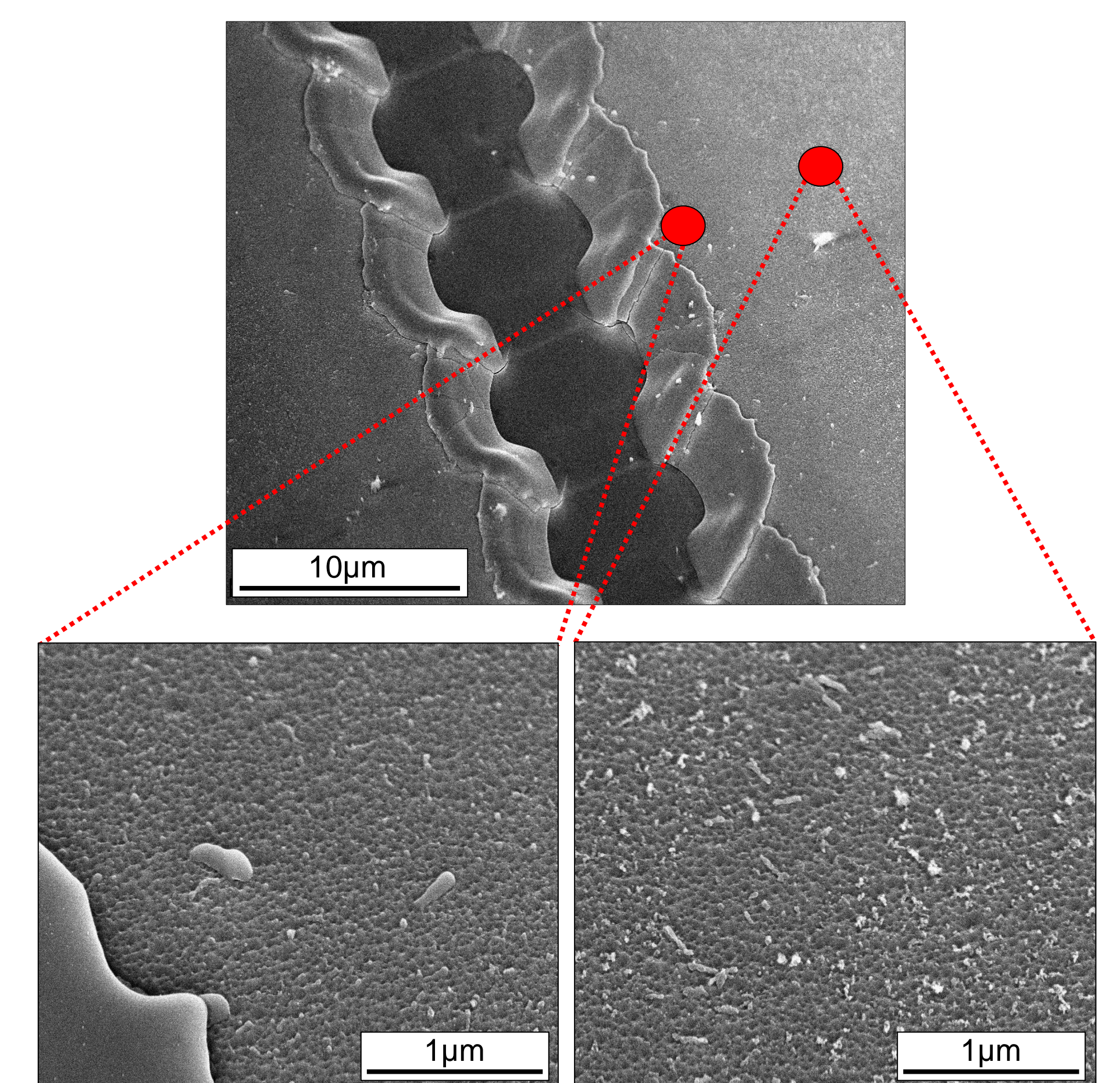
- Impact negligible  $\rightarrow$  increase of efficiency!

### Secondary effects – ZnO material modifications

#### Investigation of electrical properties with conductive AFM measurements



- Lowered current near scribe on flat TCO
- However, no current flow reduction after wet-etch!  $\rightarrow$  Surface effect, no resistivity change within whole layer



- SEM morphology suggests a correlation between amount of surface debris and current flow changes in c-AFM scans

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